



Reliability Data Report Product Family R521

LTC2801 \ LTC2802 \ LTC2803 \
LTC2804 \ LTC2850 \ LTC2851 \
LTC2852 \ LTC2854 \ LTC2855 \
LTC2856 \ LTC2857 \ LTC2858 \
LTC2859 \ LTC2861 \ LTC2870 \
LTC2871 \ LTC2872

Reliability Data Report

Report Number: R521

Report generated on: Mon Jan 18 14:04:44 PST 2016

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES ^{2, 3}
QFN/DFN	1956	1102	1448	341	0
SSOP/TSSOP	790	0630	1421	488	0
SOIC/MSOP	160	0630	0710	160	0
Totals	2,906	-	-	989	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	2198	0550	1409	52	0
SSOP/TSSOP	949	0827	1338	29	0
SOIC/MSOP	500	0937	1418	12	0
Totals	3,647	-	-	93	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	2189	0550	1409	301	0
SSOP/TSSOP	999	0526	1338	139	0
SOIC/MSOP	500	0937	1418	50	0
Totals	3,688	-	-	490	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	2242	0550	1409	224	0
SSOP/TSSOP	896	0917	1338	89	0
SOIC/MSOP	496	0937	1418	49	0
Totals	3,634	-	-	362	0

HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	148	0913	1226	123	0
Totals	148	-	-	123	0

(1) Assumes Activation Energy = 0.7 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =11.98 FITS
(3) Mean Time Between Failure in Years = 9528.14
Note: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning